

### Product Summary

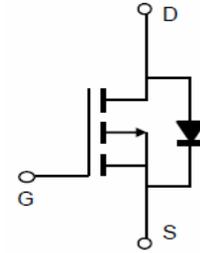
Part #	$V_{DS}$	$R_{DS(on).typ}$ (@ $V_{GS}=10V$ )	$R_{DS(on).typ}$ (@ $V_{GS}=4.5V$ )	$I_D$
EFM035P03F	-30V	3.5m $\Omega$	4.8m $\Omega$	-90A

### Description

- The EFM035P03F is the high cell density trenched P-chMOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.
- The EFM035P03F meet the RoHS and Green product requirement, 100 % EAS guaranteed with full function reliability approved.

### Application

- Super Low Gate Charge 100% EAS Guaranteed
- Green Device Available Excellent CdV/dt effect decline
- Advanced high cell density Trench technology



P-Channel MOSFET



DFN5\*6-8L

### Ordering Information:

Part NO.	EFM035P03F
Marking	035P03F ****
Packing Information	REEL TAPE
Basic ordering unit (pcs)	5000

### Absolute Maximum Ratings ( $T_C=25^{\circ}C$ )

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	-30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	-90	A
Drain Current-Pulsed <sup>(Note 1)</sup>	$I_{DM}$	-360	A
Maximum Power Dissipation	$P_D$	60	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	$^{\circ}C$

### Thermal Characteristic

Thermal Resistance, Junction-to-Ambient <sup>(Note 2)</sup>	$R_{\theta JA}$	55	$^{\circ}C/W$
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• Static Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise stated)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250uA	-30	--	--	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-30V V <sub>GS</sub> =0V	--	--	-1	nA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V V <sub>DS</sub> =0V	--	--	±100	nA
<b>On Characteristics</b> (Note 3)						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> I <sub>D</sub> =250uA	-1.0	-1.6	-2.5	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-10V I <sub>D</sub> =-30A	--	3.5	4.5	mΩ
		V <sub>GS</sub> =-4.5V I <sub>D</sub> =-15A	--	4.8	6.2	mΩ
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =-10V I <sub>D</sub> =-30A	--	90	--	S
Gate Resistance	R <sub>g</sub>	F=1.0MHz	--	4	--	Ω
<b>Dynamic Characteristics</b> (Note4)						
Input Capacitance	C <sub>ISS</sub>	V <sub>DS</sub> =-15V V <sub>GS</sub> =0V F=1.0MHz	--	5070	--	PF
Output Capacitance	C <sub>OSS</sub>		--	695	--	PF
Reverse Transfer Capacitance	C <sub>RSS</sub>		--	580	--	PF
<b>Switching Characteristics</b> (Note 4)						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =-15V I <sub>D</sub> =-30A V <sub>GS</sub> =-10V R <sub>G</sub> =3Ω,	--	23	--	nS
Turn-on Rise Time	t <sub>r</sub>		--	15	--	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		--	129	--	nS
Turn-Off Fall Time	t <sub>f</sub>		--	28	--	nS
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =-15V I <sub>D</sub> =-30A V <sub>GS</sub> =-10V	--	146	--	nC
Gate-Source Charge	Q <sub>gs</sub>		--	21.5	--	nC
Gate-Drain Charge	Q <sub>gd</sub>		--	39	--	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V I <sub>S</sub> =-30A	--	--	-1.2	V
Diode Forward Current (Note 2)	I <sub>S</sub>		--	--	-90	A

Note :

1. Repetitive rating, pulse width limited by junction temperature T<sub>J(MAX)</sub>=150°C
2. The EAS data shows Max. rating . The test condition is V<sub>DD</sub>= -25V, V<sub>GS</sub>= -10V, L= 0.1mH, I<sub>AS</sub>= -50A
3. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.

• Typical Characteristics

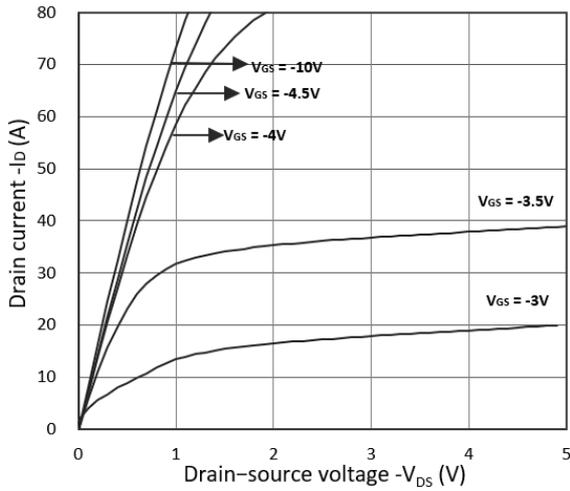


Figure 1. Output Characteristics

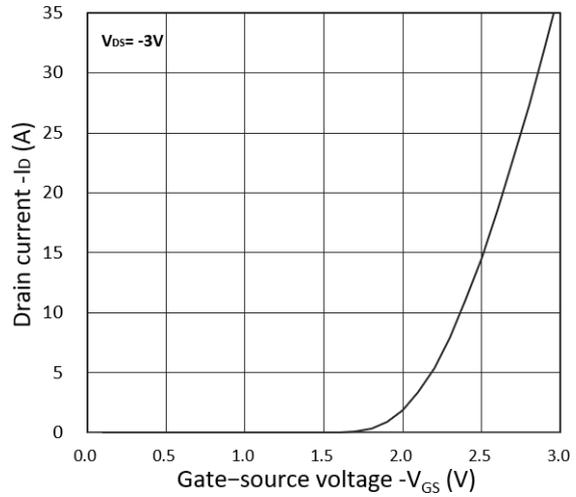


Figure 2. Transfer Characteristics

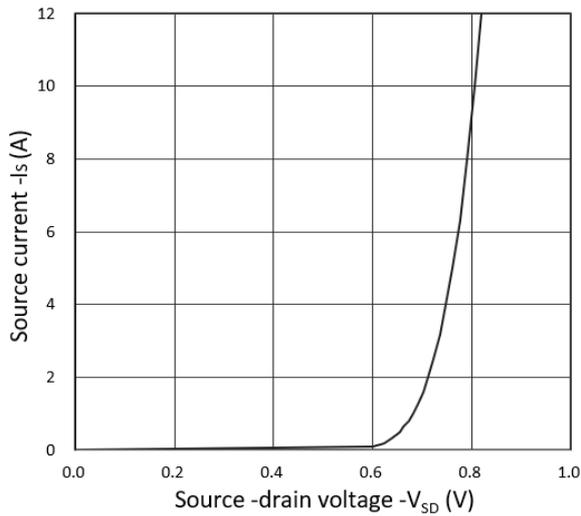


Figure 3. Forward Characteristics of Reverse

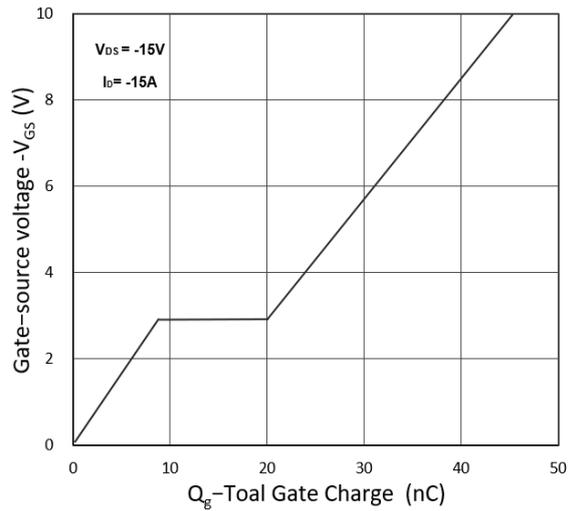


Figure 4. Gate Charge Characteristics

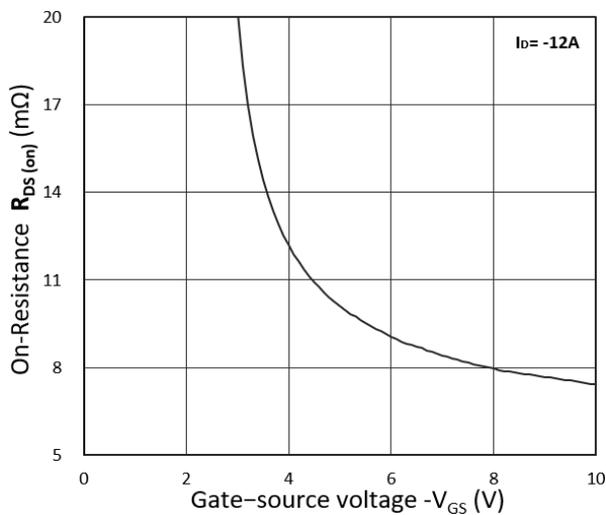


Figure 5.  $R_{DS(on)}$  vs.  $V_{GS}$

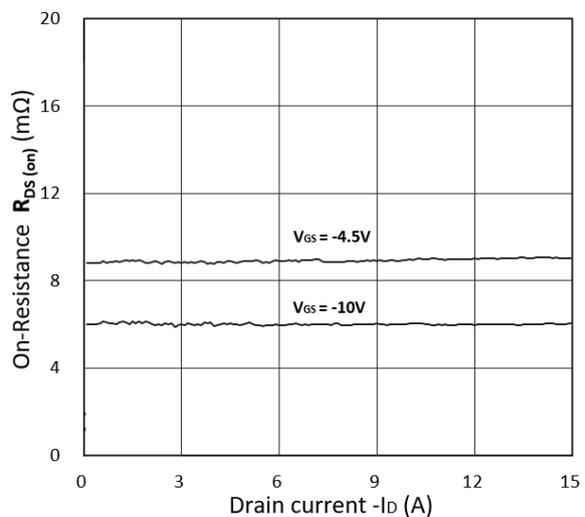


Figure 6.  $R_{DS(on)}$  vs.  $I_D$

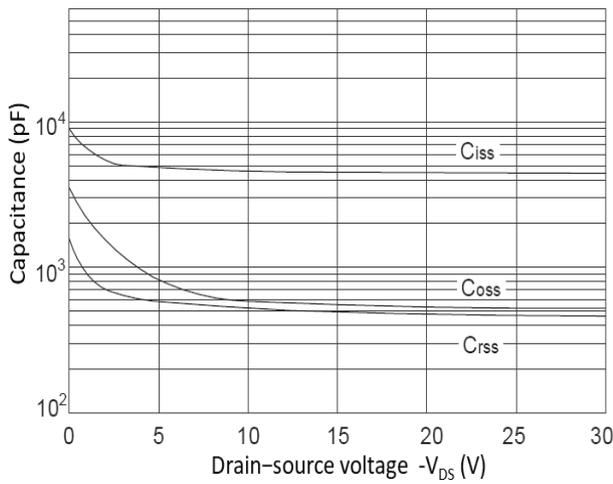


Figure 7. Capacitance Characteristics

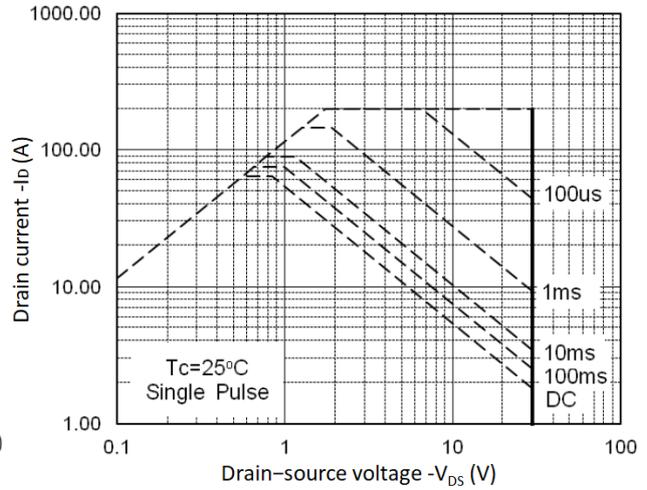


Figure 8. Safe Operating Area

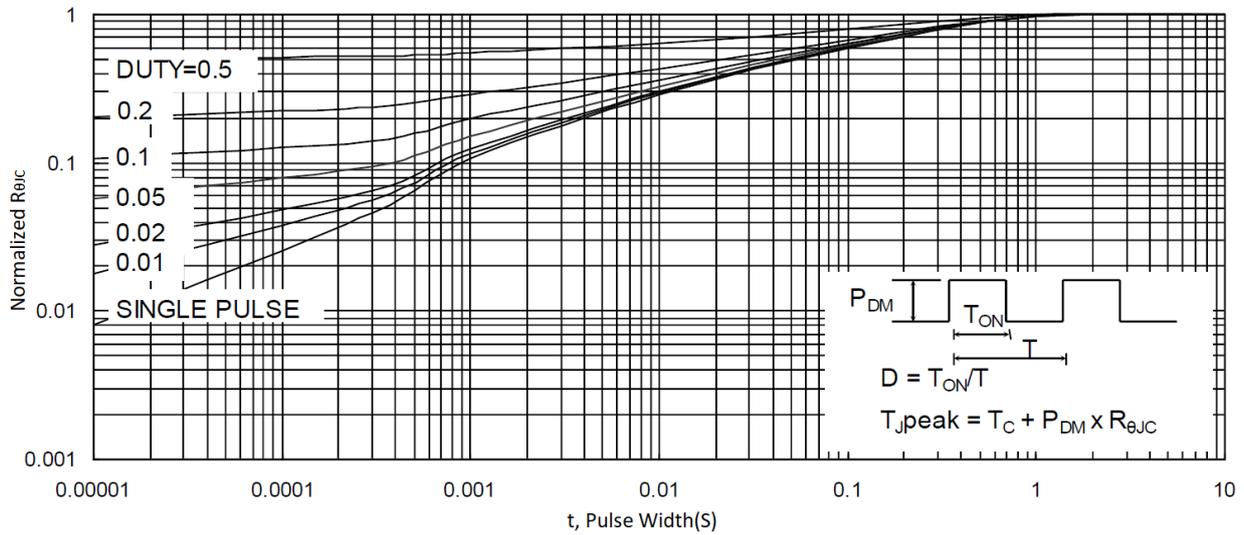


Figure 9. Normalized Maximum Transient Thermal Impedance

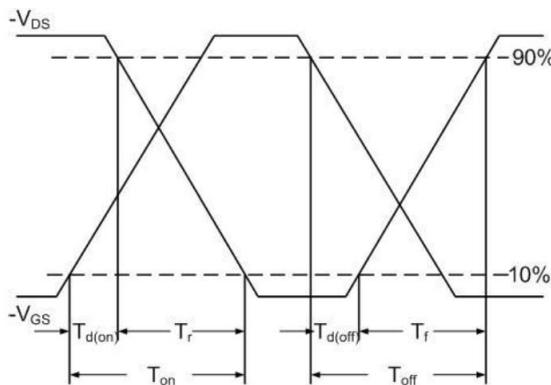


Figure 10. Switching Time Waveform

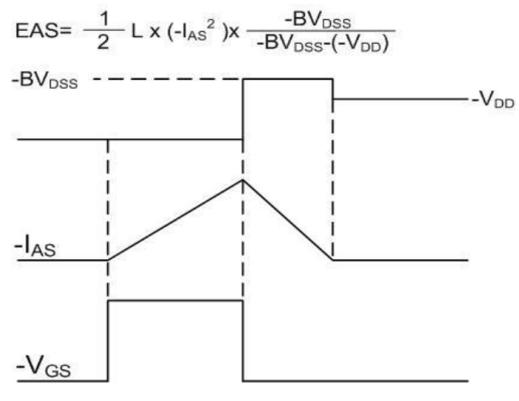
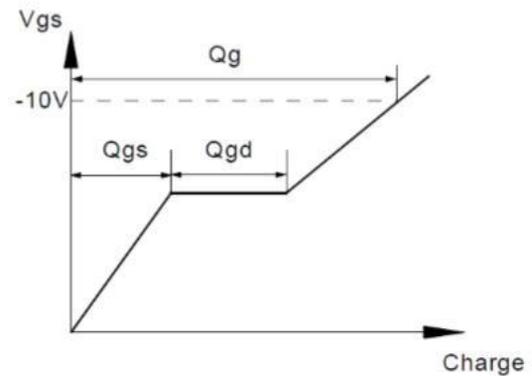
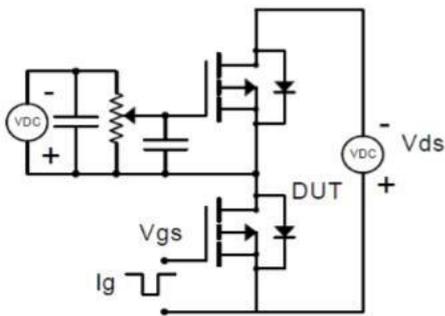
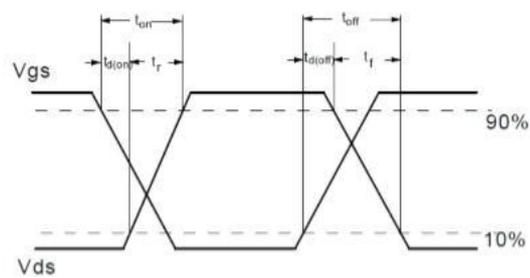
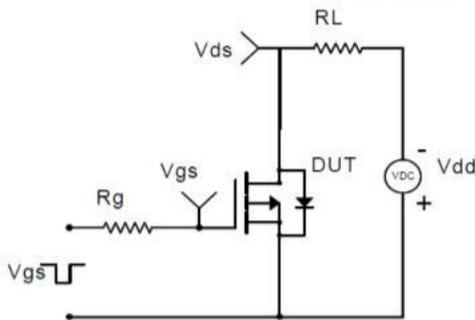


Figure 11. Unclamped Inductive Switching Waveform

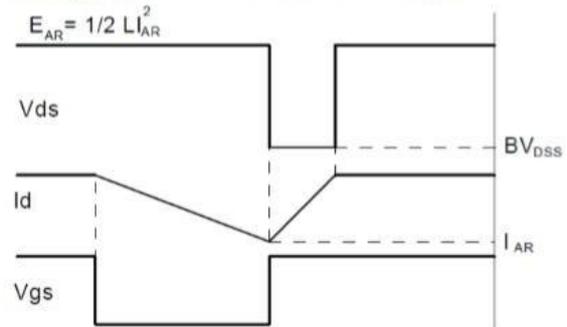
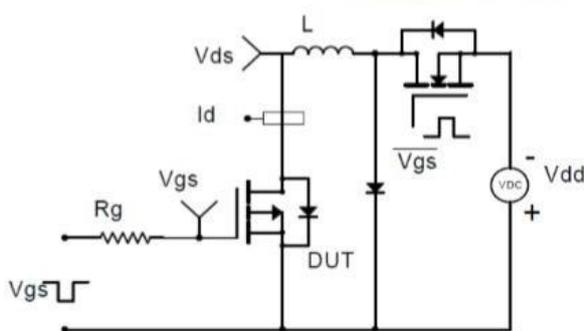
### Gate Charge Test Circuit & Waveform



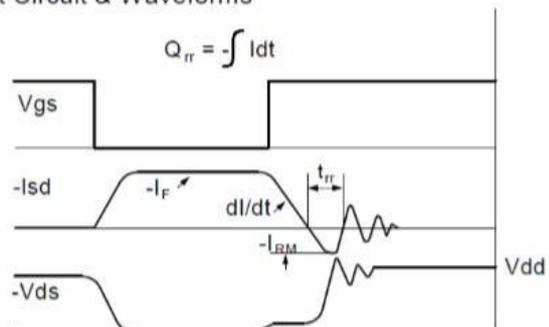
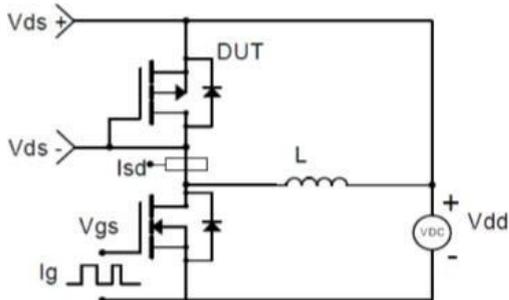
### Resistive Switching Test Circuit & Waveforms



### Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

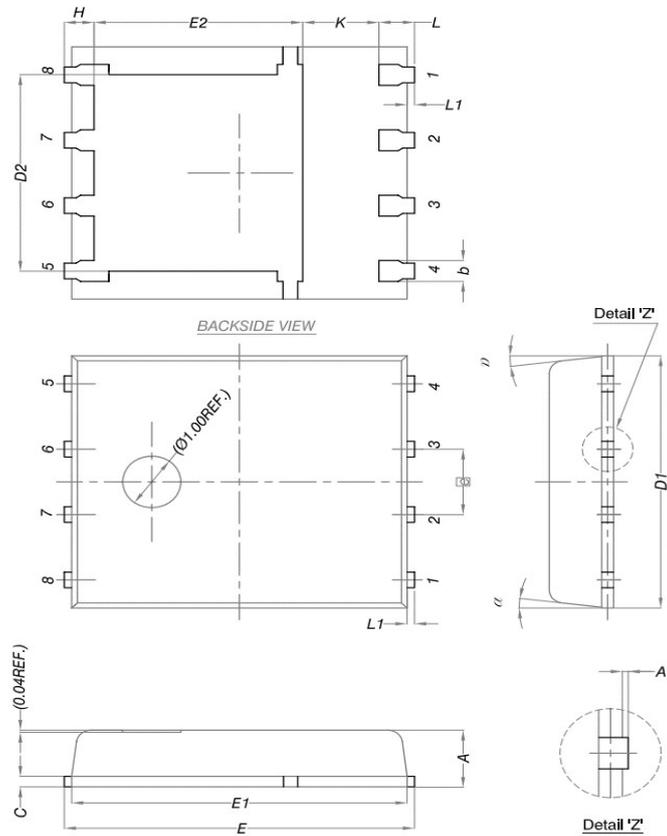


### Diode Recovery Test Circuit & Waveforms



**Figure C. Unclamped Inductive Switching Circuit & Waveforms**

## •DFN5\*6 Package Outline



DIM.	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.90	1.00	1.10
A1	0	-	0.05
b	0.33	0.41	0.51
C	0.20	0.25	0.30
D1	4.80	4.90	5.00
D2	3.61	3.81	3.96
E	5.90	6.00	6.10
E1	5.70	5.75	5.80
E2	3.38	3.58	3.78
e	1.27 BSC		
H	0.41	0.51	0.61
K	1.10	-	-
L	0.51	0.61	0.71
L1	0.06	0.13	0.20
α	0°	-	12°